

ABSTRACT

To relatively easily allow monitoring of the operation of a switching device even when the switching device is employed in an optical surface monitoring system of a substrate polishing apparatus. A substrate polishing apparatus includes a polishing table, a substrate holding head, a light source, a first optical head, a switching device, a first optical line, a second optical line, a third optical line, a first optical filter, a spectroscope, and a control device. The substrate holding head is configured to hold a substrate. The first optical head is configured to project light from the light source toward the substrate held by the substrate holding head and receive light reflected from the substrate, the first optical head being disposed inside the polishing table. The switching device includes a plurality of channels. The first optical line optically connects the light source to the first optical head. The second optical line optically connects the first optical head to one channel of the plurality of channels of the switching device. The third optical line optically connects the middle of the first optical line to the middle of the second optical line. The first optical filter is disposed in the third optical line. The spectroscope is optically connected to a downstream side of the switching device. The control device is configured to receive measurement data of the intensity of a wavelength dispersed by the spectroscope. The control device is configured to monitor the operation of the switching device based on the measurement data.

Fig. 4